

FIG.1

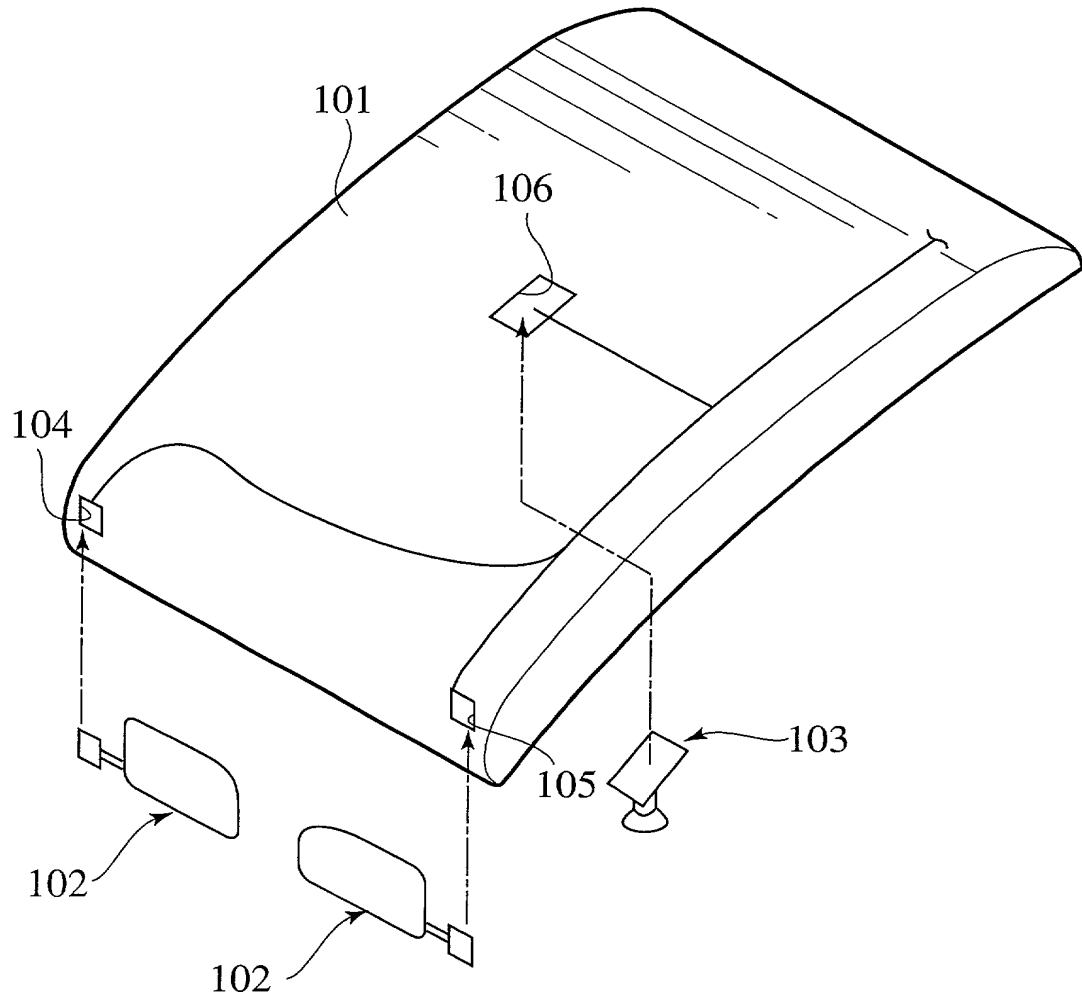


FIG.2

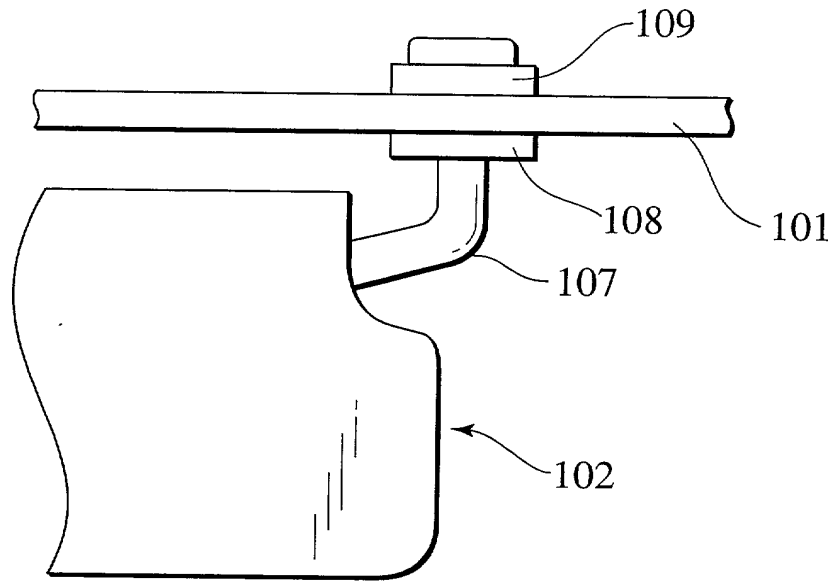


FIG.3

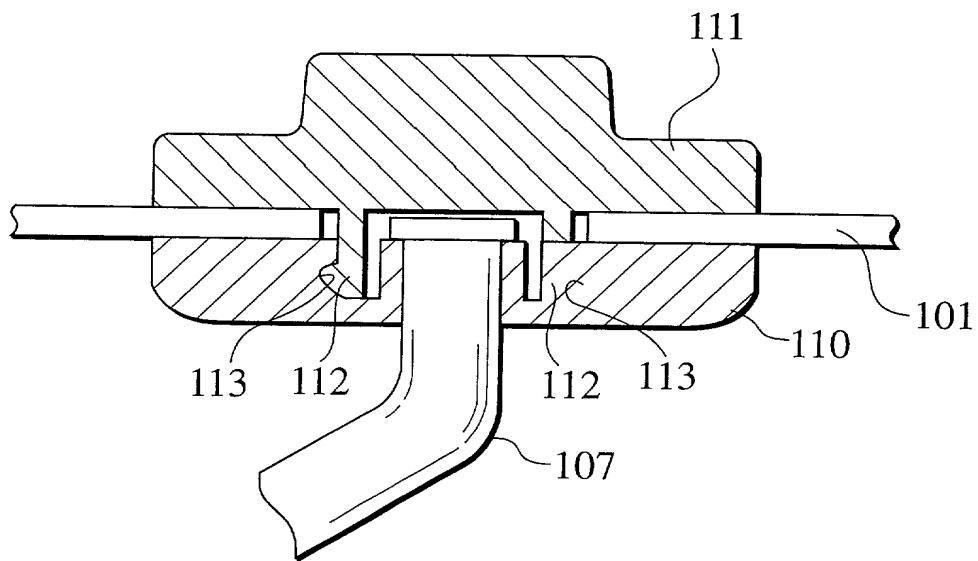
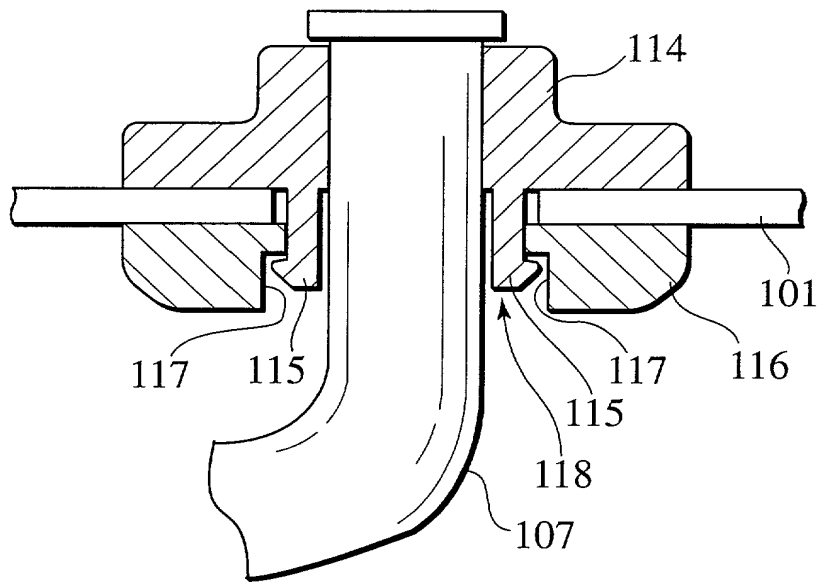


FIG.4



This exploded perspective view illustrates the assembly of a multi-layered electronic device, designated by reference numeral 1. The assembly consists of several main components:

- Top Layer (2):** A thin, flexible substrate or film with a central opening and two circular features labeled 2A and 2B.
- Central Core (20):** A complex, multi-layered structure with various internal components and features labeled 21, 22, 23, 24, 27, 29, 30, and 31. It appears to be the main functional unit of the device.
- Bottom Layer (3):** A larger, rigid substrate or base with a central opening and a flange-like edge labeled 3A.
- Base Assembly (4):** A circular, multi-layered base structure with various internal components and features labeled 5, 7, 8, 9, 10, 11, 12, 14, 16, 18, and 19. It includes a central protrusion and a circular opening.

Vertical dashed lines indicate the alignment and assembly path of the components, showing how they fit together to form the complete device 1.

FIG.6

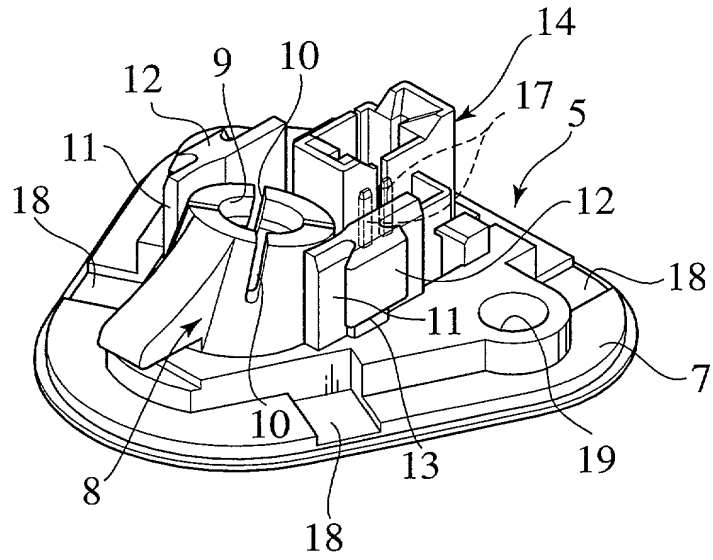


FIG.7

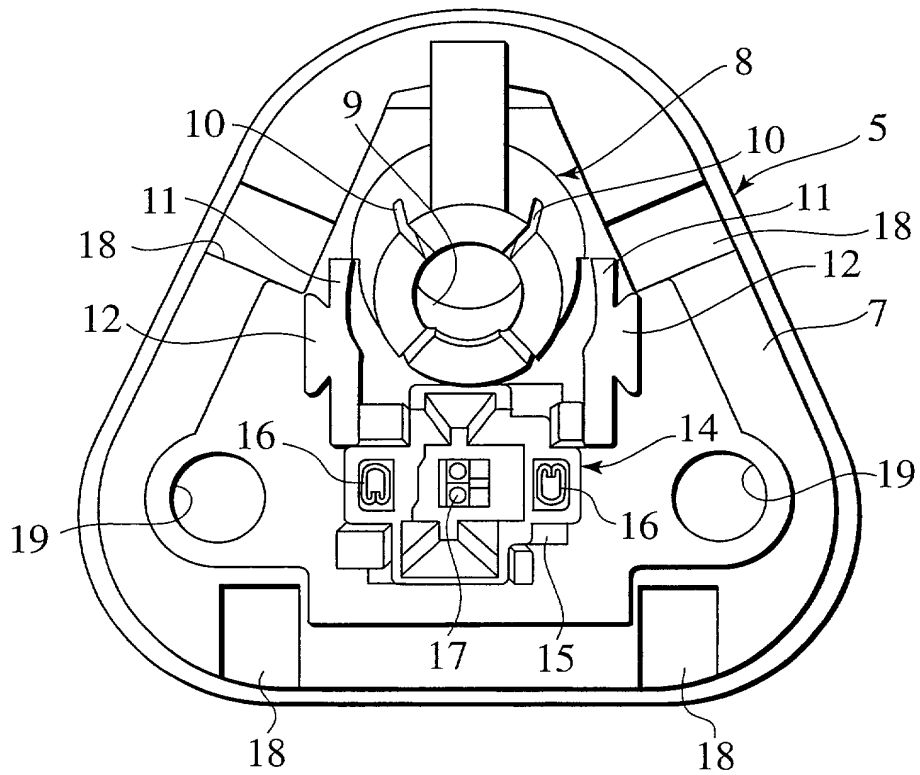


FIG. 8

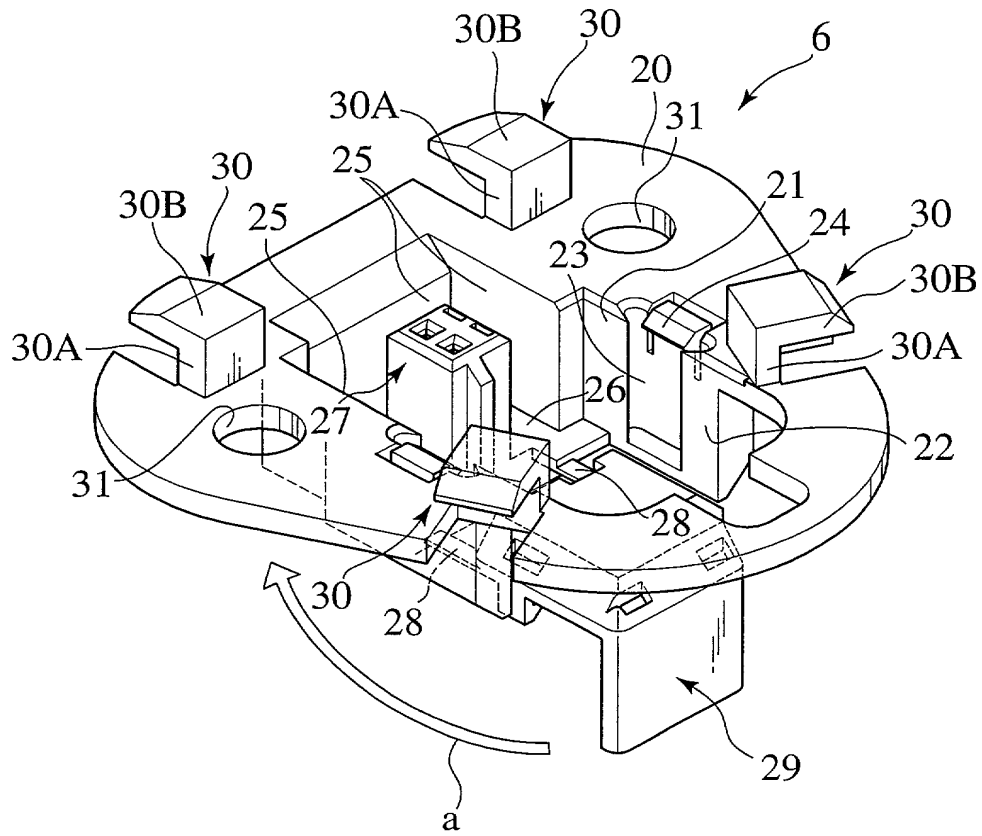


FIG.9

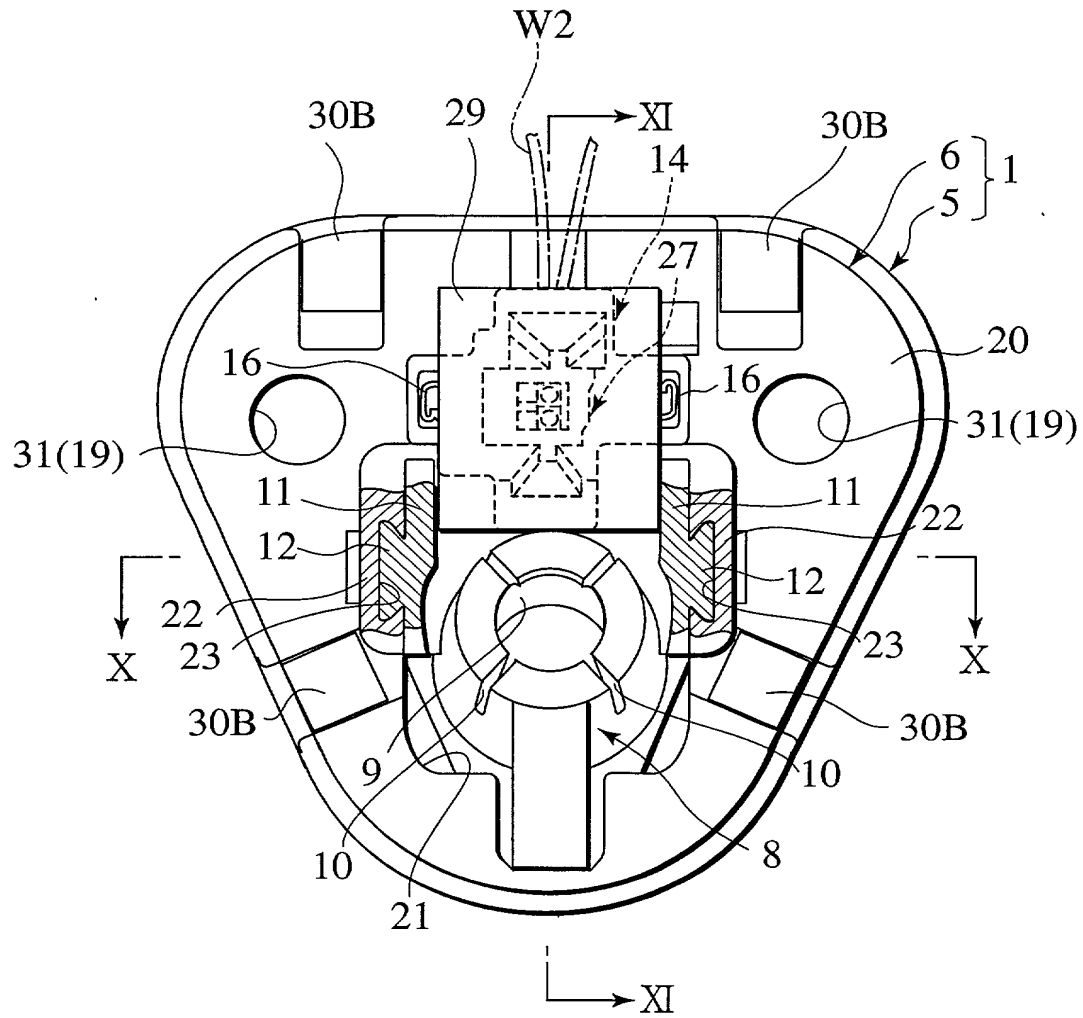


FIG.11

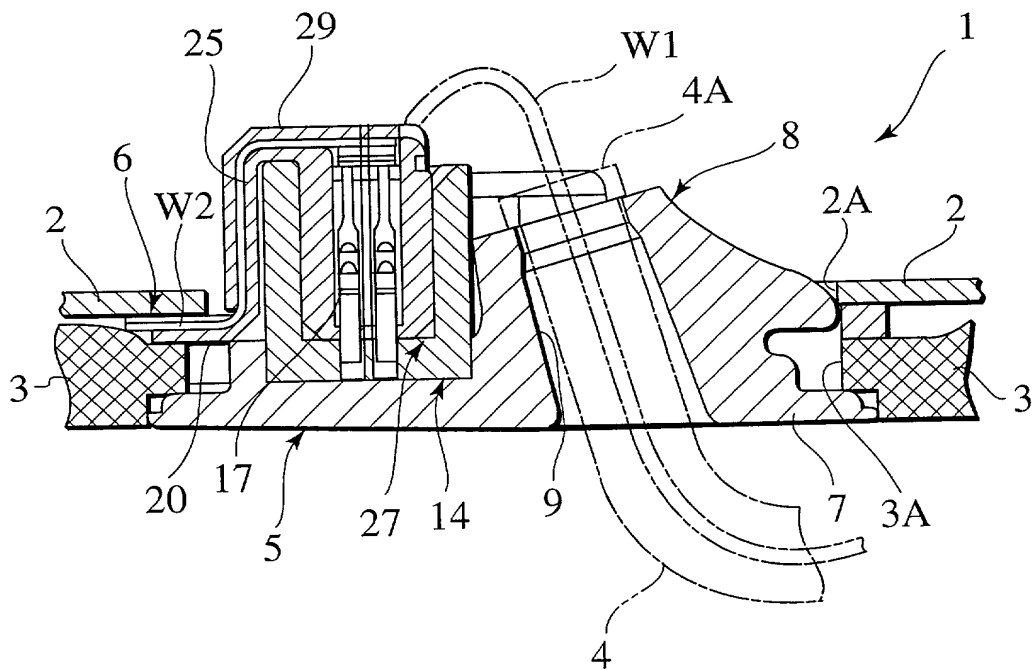


FIG.12

